Future leading technology

ADVANCED
LINK
TECHNOLOGY

ALT

Executive Summary : ALT is a wafer Test House and also service of back-end Process.

Company Overview

Advanced Link Technology

Establishment	**July 23th, 2003**
CEO	**BT Chun**
COO	**EC Lee**
Capital	**US$ 3.2Million**
Employees	**200**
Homepage	**www.alt-s.kr**
Youtube	**https://youtu.be/JQ-FnrFrwlU**

Business Scope

ALT & AGP

Display Driver IC (DDI)
Wafer Test, COF PKG Test

CMOS Image Sensor (CIS)
Wafer Test, PKG VT test

System On Chip (SOC)
Wafer Test

Power Management IC & Discrete (PMIC)
Wafer Test

Back-End Process
Back Grinding, Dicing, Re-con, P&P, Ring-Cut, Laser Grooving
Subsidiary Company, AGP
CIS PKG PLCC, CLCC, LGA, BGA (Automotive AEC_Q100)

Location

Advanced Link Technology

Executive Summary

ALT is located in 15min away from CheongJu Airport and 2hr away from Incheon Airport by driving

TEST PLANT (CheongJu City)

Address

(28122) 82-19, Gwahaksaneop 1-ro, Oksan-myeon,
Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea

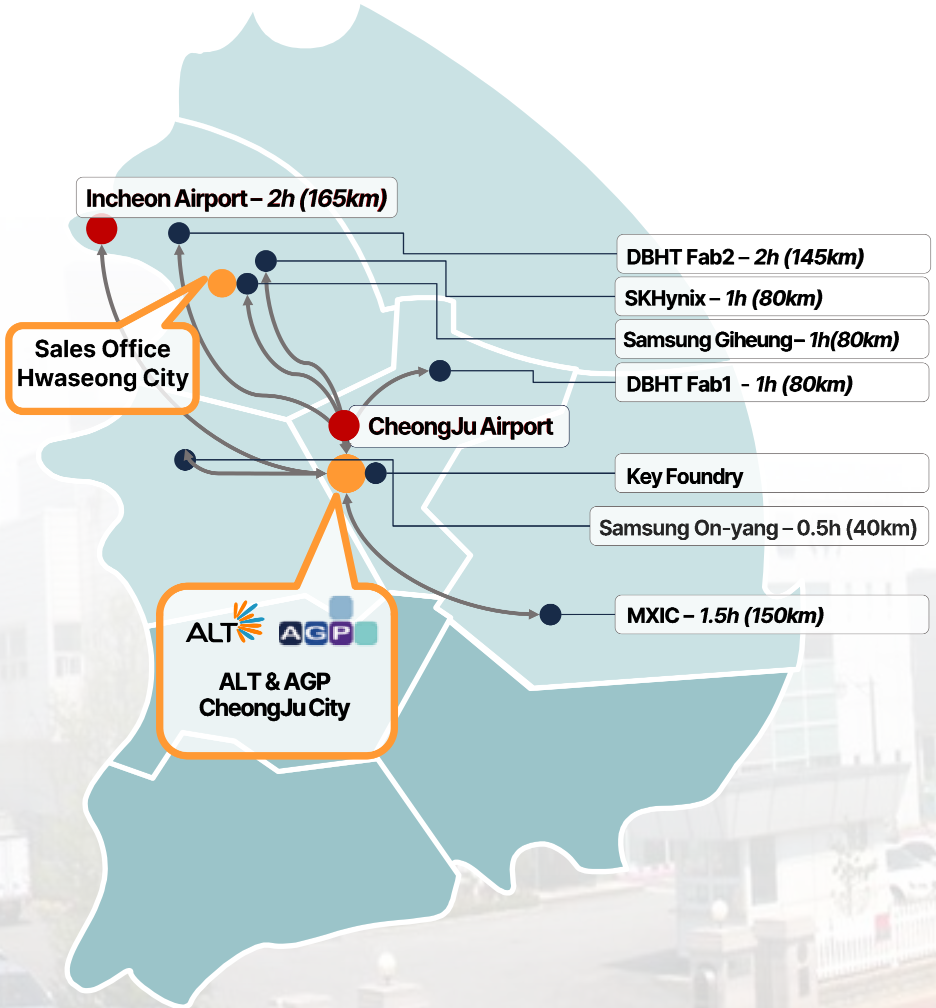
Tel. 043-711-2500

Fax. 043-711-2505

SALES OFFICE (HwaSeong City)

Address

(18449) 815, WonheeCastle, 1-9, Seogu-dong, Hwaseong-si,
Gyeonggi-do, Republic of Korea



Milestone

Advanced Link Technology

2003
- ALT Establishment
- ND2 MP for LGD DDI

2006
- ND2 FT MP for S.LSI, LGD, Sony DDI
- Co-Development with Hynix CIS

2007
- ND2 MP for DBH DDI
- IP750EX MP for Hynix CIS

2012
- IP750/ND2 MP for MCU
- ETS200T/STA2100/IMP8 MP for Magnachip

2016
- ND4S MP for 12" DDI

2018
- ND4S MP for S.Fdry_DDI

2019
- T2K ISS MP for SK Hynix CIS
- Recon Capa. Invest. for CIS
- COG Capa. Extension for DDI

2020
- COG MP for DDI
- Rim Cut & Wafer Test MP for S.Fdry IGBT

2022
- Diamond-X Wafer Test Invest. for S.LSI DDI
- ND4S Wafer Test Capa. Extension
- Recon Coating/Removal Invest. for 50MP CIS
- SiC Power Device MP for PMS, SKP

2023
- UFlex MP for Memory-Controller
- Rim Cut Capa Extension
- Laser Grooving(Femto-sec) Invest.
- SiC Dicing MP

2023 27th Jul

IPO in Kosdaq

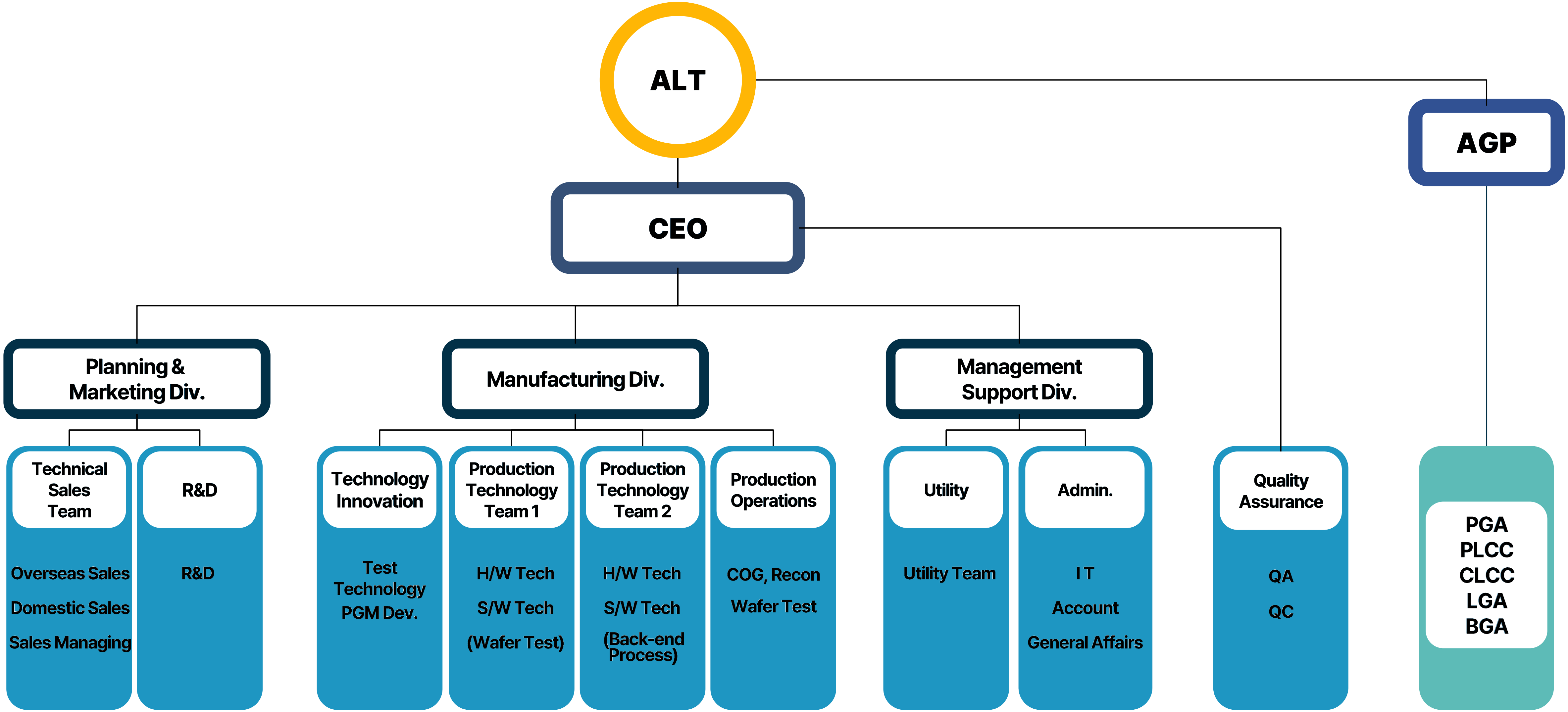
2024
- UFlex-Plus for S.Fdry AP of Galaxy Watch
- T2K MP for S.LSI CIS

Executive Summary

ALT start CIS wafer test biz from 2007, Recon biz from 2019 and Recon Coating/removal from 2022

Organization

Advanced Link Technology



ALT

AGP

CEO

Planning & Marketing Div.

- Technical Sales Team
  - Overseas Sales
  - Domestic Sales
  - Sales Managing
- R&D
  - R&D

Manufacturing Div.

- Technology Innovation
  - Test Technology PGM Dev.
- Production Technology Team 1
  - H/W Tech
  - S/W Tech
  - (Wafer Test)
- Production Technology Team 2
  - H/W Tech
  - S/W Tech
  - (Back-end Process)
- Production Operations
  - COG, Recon
  - Wafer Test

Management Support Div.

- Utility
  - Utility Team
- Admin.
  - I T
  - Account
  - General Affairs

Quality Assurance

- QA
- QC

AGP

- PGA
- PLCC
- CLCC
- LGA
- BGA

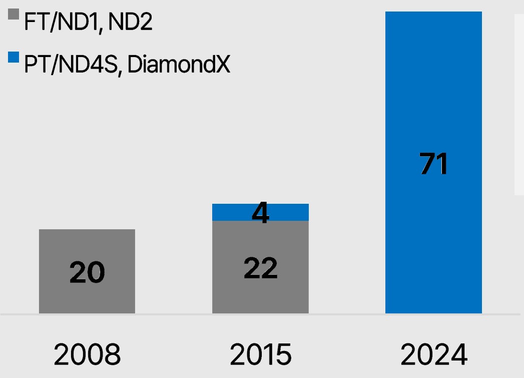
Capacity

Advanced Link Technology

Executive Summary

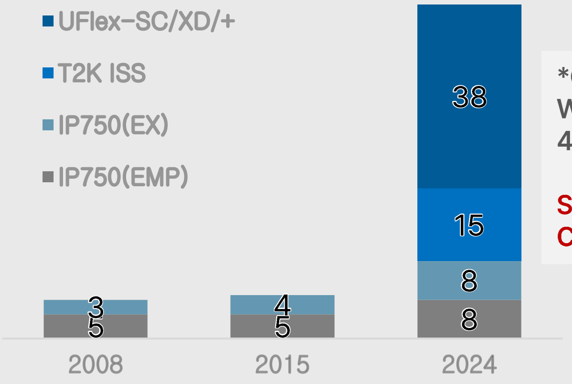
ALT has about **150 test set** and has tested DDI, CIS, ASIC, SOC, Discrete and PMIC

A DDI Test Capacity : 71 Set



*Capacity:
Wafers Test
15,000sls/month

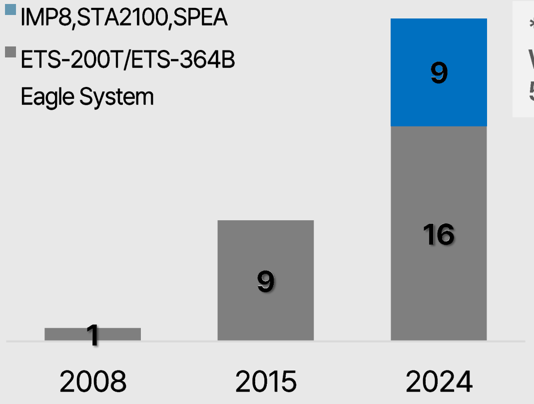
B CIS 31 Set & SOC 38 Set



*Capacity:
Wafers Test
45,000sls/month

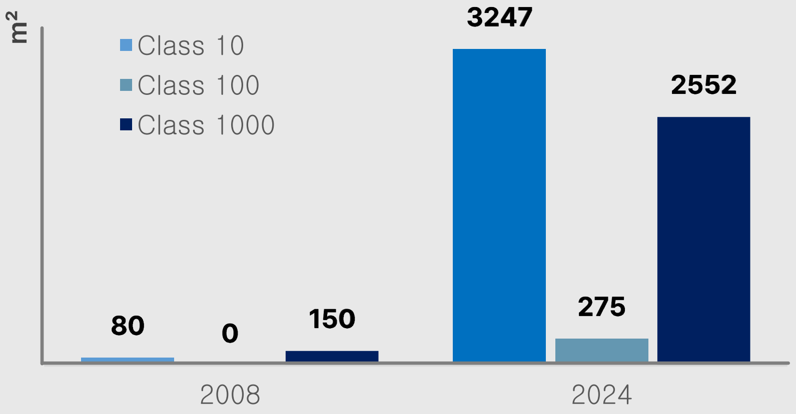
SOC 26Ksls/month
CIS 25Ksls/month

C Discrete IC(IGBT,MOSFET) Capacity : 25 Set



*Capacity:
Wafers Test
50,000sls/month

D Improvement of Class Room



Wafer Test Process Flow

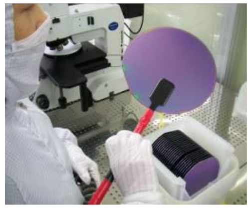
Advanced Link Technology

Wafer Test Process

Incoming

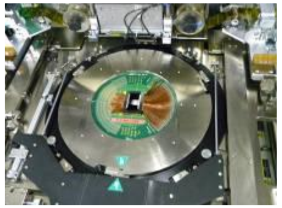
- Wafer (6″, 8″, 12″)

IQC



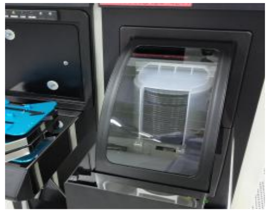
- Image High & low Power Scope
- Clean Room (10 Class)

Wafer Test



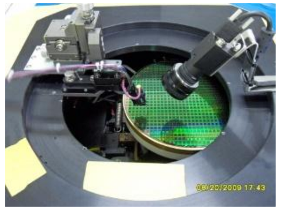
- Electrical Testing
- Program Development

AVI



- Auto Visual Inspection

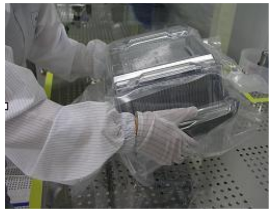
Inking



- Reject dies inking

QVI

Packing



QPI

Ship

Final Test Process Flow

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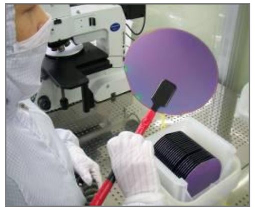
Final Test Process - DDI

Incoming

- TCP, COF
- 35mm, 48mm, 70mm

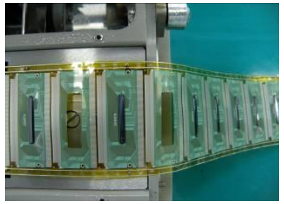
IQC



Final Test

- Electrical Testing
- Program Development

AVI / Split

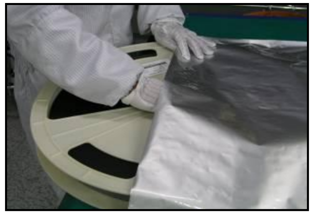


- All Inspection
- Split
- Auto Winder

QVI

- Visual & Sheet Inspection
- Sampling 50Units/Lots
- Auto Winder

Packing



- Barcode Labeling
- Packing Machine

QPI

Ship

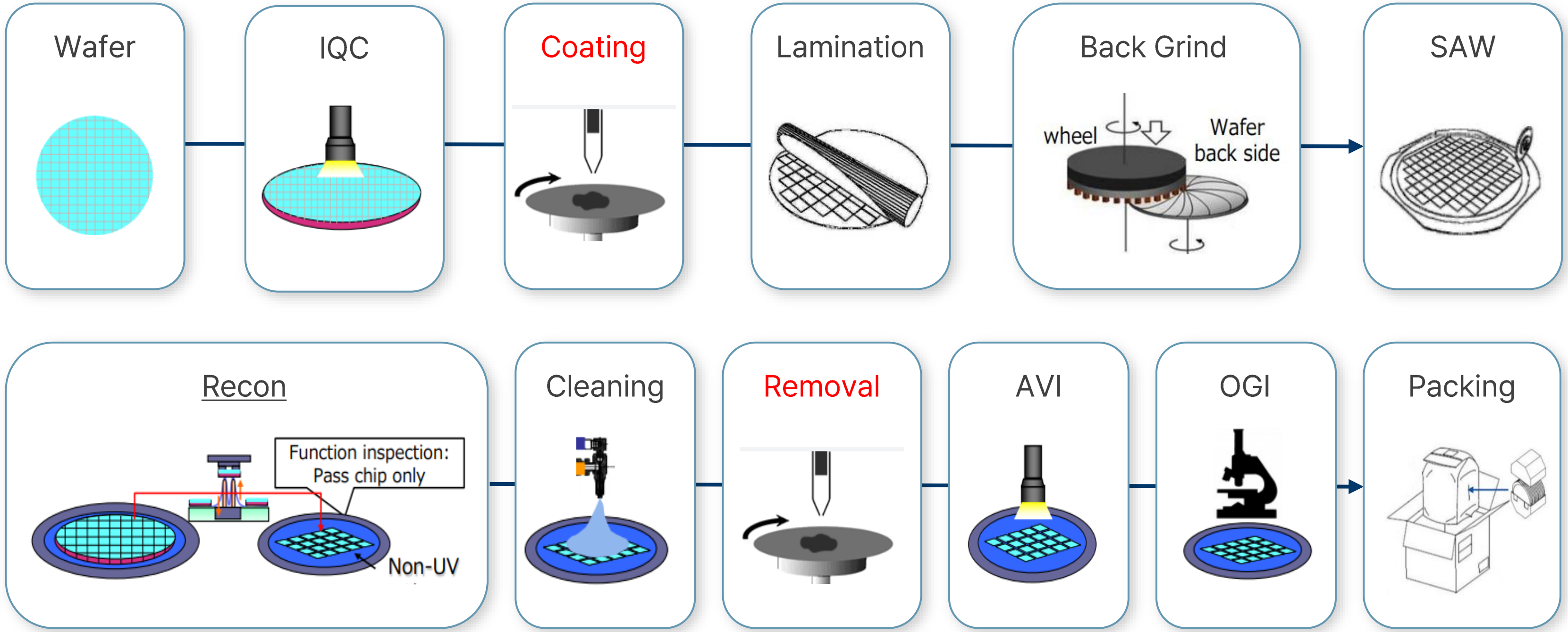
- Out box Packing

ReCon* Process

***Reconstruction**

Advanced Link Technology

ReCon(*Reconstruction) Process



Why ALT Recon

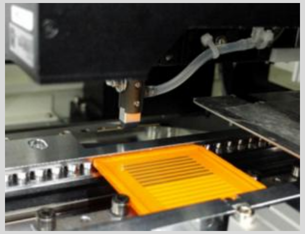
- ❖ Superior Quality & yield – Class 10 , Auto Visual inspection
- ❖ Expert Engineering team – More than 10 years experience
- ❖ Happy customers – 100% meet the delivery date and good price
- ❖ Cutting-edge In line machines
- ❖ High Reliability – In line R/T, and F/A

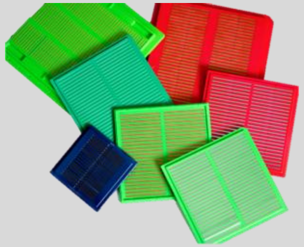
COG Process (DDI)

Advanced Link Technology

Executive Summary
ALT's COG rearrange selected good chips to enables customers to speed up and improve subsequent processes, aiding in production schedules.

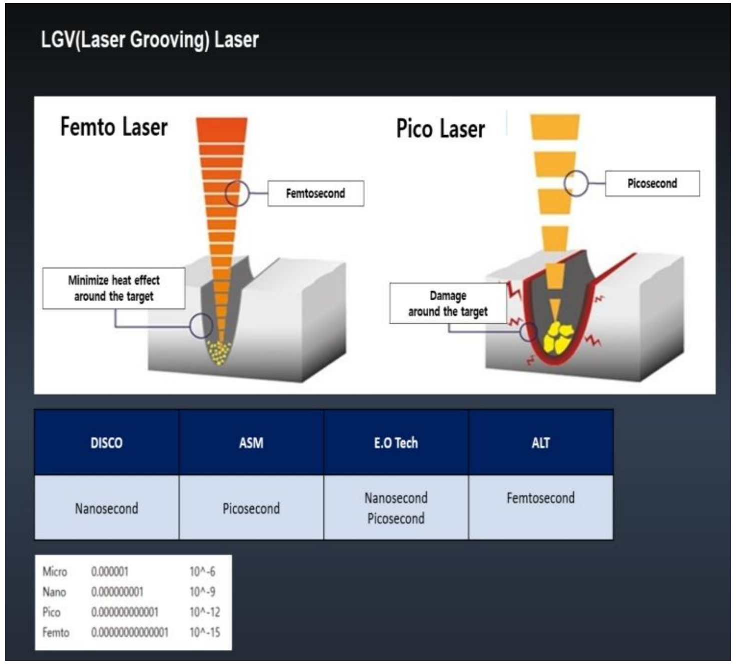
- Wafer
- IQC/AVI
- Lamination
- Back Grind
- Marking
- Laser Grooving
- SAW
- Pick & Place
- AVI
- VI
- Packing





Why ALT COG

- **B/G Max. Capability : 35um(8" and 12")**
- **Laser grooving : 12inch low-K, S/L 45um under**
- **AVI detective : 100% fail die verify and Chip tracking**



LGV(Laser Grooving) Laser

DISCO	ASM	E.O Tech	ALT
Nanosecond	Picosecond	Nanosecond Picosecond	Femtosecond

Micro	0.000001	10^-6
Nano	0.000000001	10^-9
Pico	0.000000000001	10^-12
Femto	0.000000000000001	10^-15

Ring-Cut Process (IGBT, Power IC)

Advanced Link Technology

Executive Summary
ALT has the Rim Cut for high voltage power device with taiko type wafer after wafer test.

ALT Rim cut, Core competence

- First development and MP start
- Kerf width of Rim cut : 40um
- Void, Debris free, NO handling risk

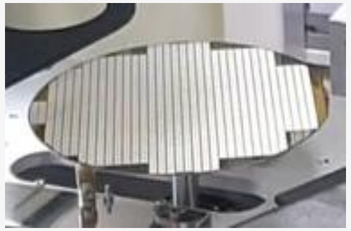
"ALT, developed a new Rim Cut process for Taiko wafer, full automation system from Rim cut to foil mount"

Rim or Ring Cut Process (IGBT, Power IC)

Loading 1

Wafer input

Pre Align 2



Wafer align

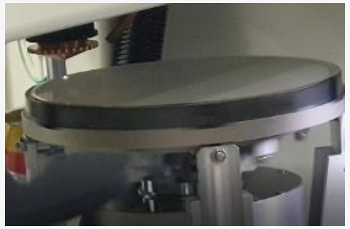
Flip 3

Wafer reveres

Post Align 4

Wafer align for laser cut

Laser cut 5

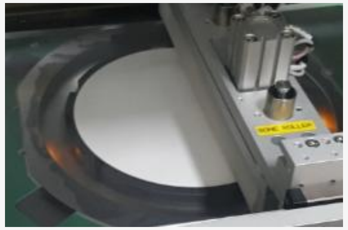


Rim cut by laser

Ring remove 6

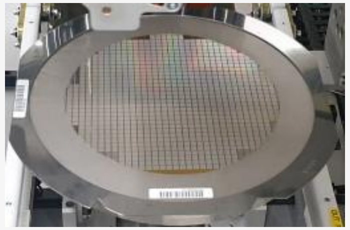
Rim removal

Foil mount 7



Mount tape with Ring frame

Labeling 8



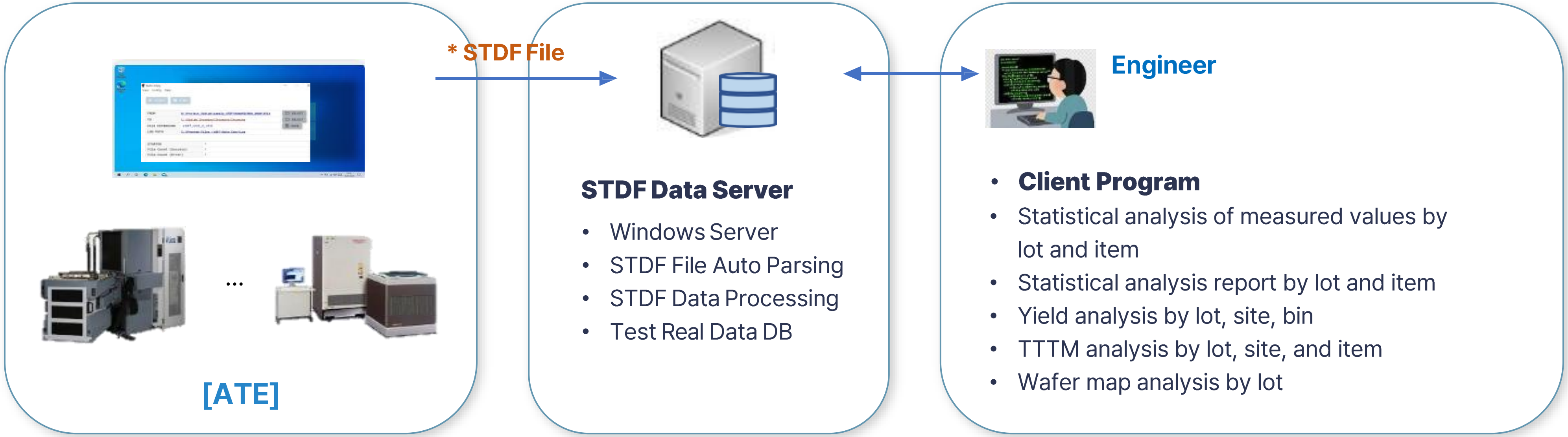
Label on the tape

Real time Bin Monitoring Software

Advanced Link Technology

Executive Summary
ALT has the analysis software to define real time binning and real root cause.

Bin Monitoring System



STDF Data Server

- Windows Server
- STDF File Auto Parsing
- STDF Data Processing
- Test Real Data DB

- **Client Program**
- Statistical analysis of measured values by lot and item
- Statistical analysis report by lot and item
- Yield analysis by lot, site, bin
- TTTM analysis by lot, site, and item
- Wafer map analysis by lot

What we provide:

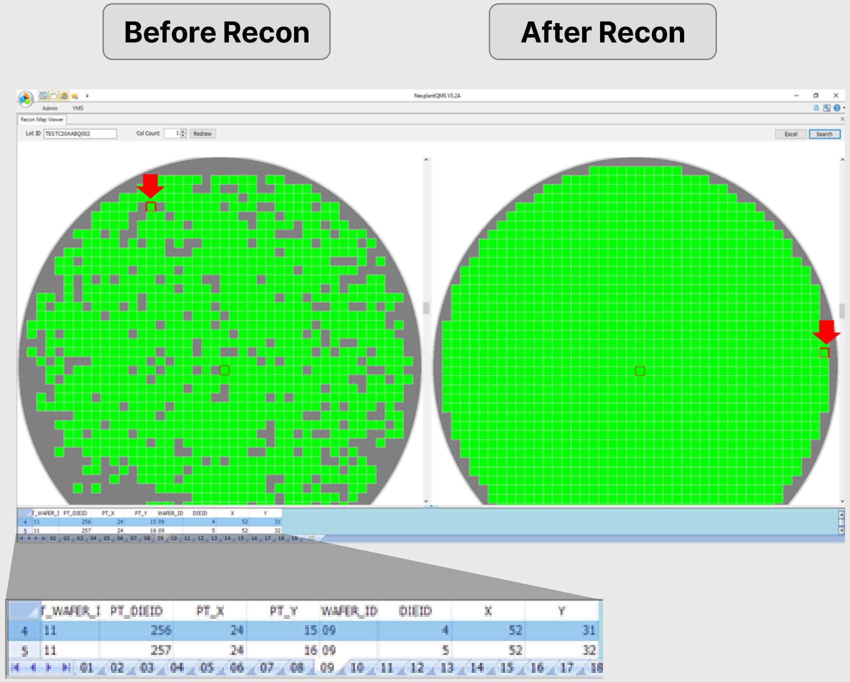
- Data Unity: Build a measurement data DB on the server and analyze the same data for multiple users
- Securing the foundation for introducing an alert system based on lot-specific measurement data: ex. TTTM Email Alert (**tool to tool matching of hardware**)
- Process improvement: Identifying defect levels through statistical analysis of measured values and chart analysis (ex. **Improvement of yield deviation by site**)
- Establishment of a data database of measured values: writing a quick and accurate analysis report (**securing global competitiveness**)
- **Immediate response to customer requests (defect cause analysis/report)**: Provide utmost customer satisfaction

Recon Traceability System

Advanced Link Technology

Executive Summary
ALT has the QMS Mapping system for Recon Traceability

Die position can be traced before and after the Recon.



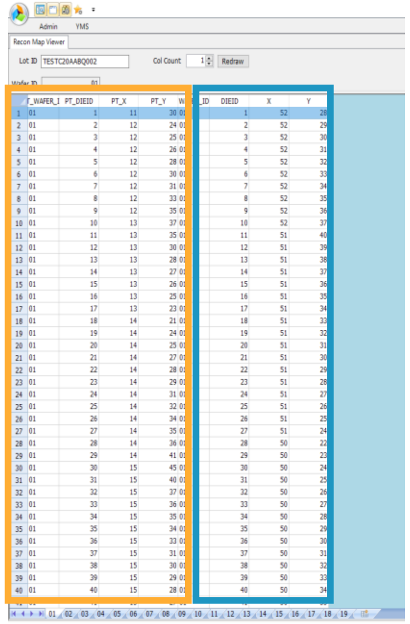
	T_WAFER_I	PT_DIEID	PT_X	PT_Y	WAFER_ID	DIEID	X	Y
4	11	256	24	15	09	4	52	31
5	11	257	24	16	09	5	52	32

Coordinates can be checked on the table.

Example)

Wafer TEST map coordinates: Wafer No. 11, X-24, Y-15
= RECON map coordinates: Wafer No. 9, X-52, Y-31

After Recon, Wafer test map coordinates can be checked with die map coordinates.



	T_WAFER_I	PT_DIEID	PT_X	PT_Y	W _ID	DIEID	X	Y
1	01	1	11	30	01	1	52	28
2	01	2	12	24	01	2	52	29
3	01	3	12	25	01	3	52	30
4	01	4	12	26	01	4	52	31
5	01	5	12	28	01	5	52	32
6	01	6	12	30	01	6	52	33
7	01	7	12	31	01	7	52	34
8	01	8	12	33	01	8	52	35
9	01	9	12	35	01	9	52	36
10	01	10	13	37	01	10	52	37
11	01	11	13	35	01	11	51	40
12	01	12	13	30	01	12	51	39
13	01	13	13	28	01	13	51	38
14	01	14	13	27	01	14	51	37
15	01	15	13	26	01	15	51	36
16	01	16	13	25	01	16	51	35
17	01	17	13	23	01	17	51	34
18	01	18	14	21	01	18	51	33
19	01	19	14	24	01	19	51	32
20	01	20	14	25	01	20	51	31
21	01	21	14	27	01	21	51	30
22	01	22	14	28	01	22	51	29
23	01	23	14	29	01	23	51	28
24	01	24	14	31	01	24	51	27
25	01	25	14	32	01	25	51	26
26	01	26	14	34	01	26	51	25
27	01	27	14	35	01	27	51	24
28	01	28	14	36	01	28	50	22
29	01	29	14	41	01	29	50	23
30	01	30	15	45	01	30	50	24
31	01	31	15	40	01	31	50	25
32	01	32	15	37	01	32	50	26
33	01	33	15	36	01	33	50	27
34	01	34	15	35	01	34	50	28
35	01	35	15	34	01	35	50	29
36	01	36	15	33	01	36	50	30
37	01	37	15	31	01	37	50	31
38	01	38	15	30	01	38	50	32
39	01	39	15	29	01	39	50	33
40	01	40	15	28	01	40	50	34

Wafer test **Recon**

After recon, each die's original position on the wafer can be traced.

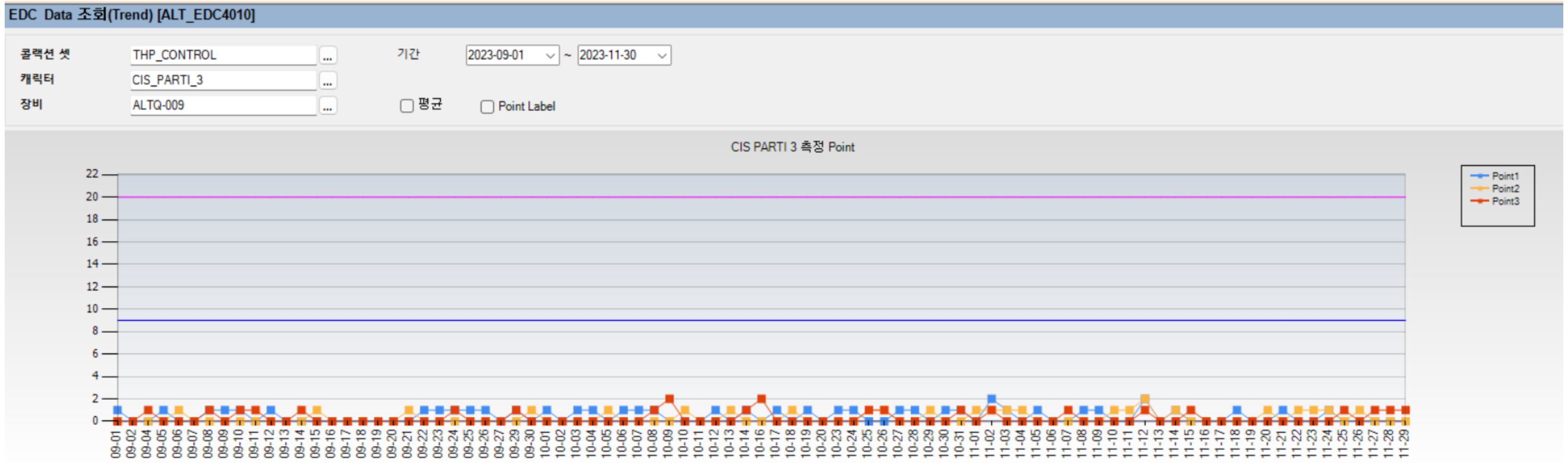
- 🟧 **Wafer Test map coordinates**
(Wafer No, Die No, X coordinate, Y coordinate)
- 🟦 **RECON map coordinates**
(Wafer No, Die No, X coordinate, Y coordinate)

Test & Recon Line Conditions System

Advanced Link Technology

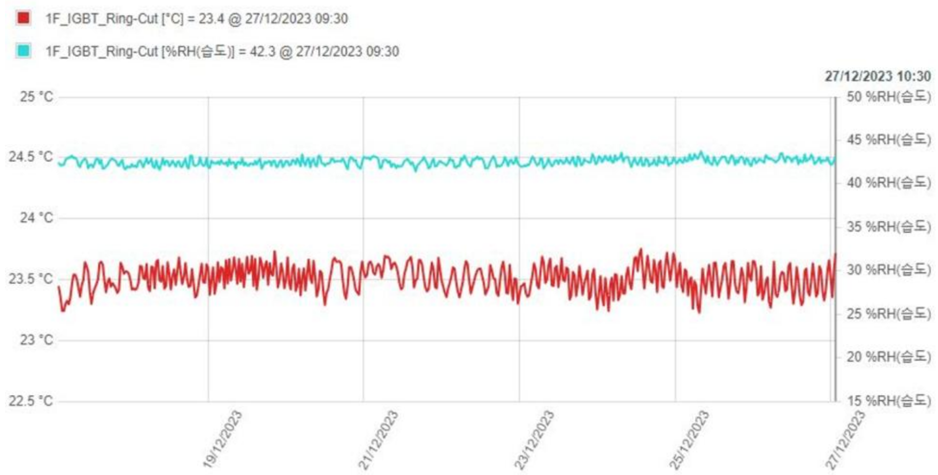
Executive Summary
ALT strictly controls Line conditions, optimizing for CIS test and Recon

Particle control


EDC Data 조회(Trend) [ALT_EDC4010]

콜렉션 셋 THP_CONTROL ...
캐릭터 CIS_PARTI_3 ...
장비 ALTQ-009 ...
기간 2023-09-01 ~ 2023-11-30
☐ 평균 ☐ Point Label

Temp. and Humidity control



- ❖ **ALT has 10 Class line from Wafer Test to Recon** (Test~B/G+Sawing+Recon)
- ❖ **ALT strictly control the environment through the system**
  → With sensors installed in clean rooms, ALT constantly monitor particle counts, temperature and humidity.
- ❖ **The entire process is done on one site.**
  → Only ALT can provide this in Korea.
  →Shortest TAT : Save 3days of logistic time

Quality System

IATF16949:2016

CERTIFICATE
OF REGISTRATION

This is to certify that:

ALT Co., Ltd.

82-19, Gwahaksaneop1-ro, Oksan-myeon, Heungdeok-gu, Cheongju-si,
Chungcheongbuk-do, 28122, Korea

Operates a

QUALITY MANAGEMENT SYSTEM

Which complies with the requirements of

IATF 16949:2016

For the following scope of registration:

Manufacturing of Machining for Semiconductor Parts
Exclusion – Product Design

Certificate No.: AUTO41269
IATF Database No.: 0395275

Issue Date: 19 April 2021
Expiry Date: 18 April 2024

Frank Camasta
Global Head of Technical Services
SAI Global Assurance

Dusan Nikolic
Automotive Technical Manager
Global Scheme Owner

Certified System
IATF 16949

SAI GLOBAL

ISO9001:2015

CERTIFICATE
OF REGISTRATION

This is to certify that:

ALT Co., Ltd.

82-19, Gwahaksaneop 1-ro, Oksan-myeon, Heungdeok-gu, Cheongju-si,
Chungcheongbuk-do, 28122, Republic of Korea

operates a

QUALITY MANAGEMENT SYSTEM

which complies with the requirements of

ISO 9001:2015

for the following scope

Testing of Semiconductor Parts (LDI, CIS, PMIC, MCU)

Certificate No: QMS42327

Issued: 2019.08.09
Expires: 2022.11.29

Originally Certified: 2007.11.30
Current Certification: 2019.11.30

Heather Mahon
Global Head of Technical Services
SAI Global Assurance

Certified System
ISO 9001

JAS-ANZ

IAF

Registered by:

SAI GLOBAL

ISO14001:2015

CERTIFICATE
OF REGISTRATION

This is to certify that:

ALT Co., Ltd.

2F, 82-19, Gwahaksaneop 1-ro, Oksan-myeon, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28122, Republic of Korea,

operates a

ENVIRONMENTAL MANAGEMENT SYSTEM

which complies with the requirements of

ISO 14001:2015

for the following scope

Manufacture of Machining for Semiconductor Parts
Providing of inspection service for Semiconductor Parts

Certificate No: EMS41778

Issued: 2021.03.02
Expires: 2024.03.01

Originally Certified: 2021.03.02
Current Certification: 2021.03.02

Frank Camasta
Global Head of Technical Services
SAI Global Assurance

Certified System
ISO 14001

JAS-ANZ

IAF

Registered by:

SAI GLOBAL

Customers

SAMSUNG 삼성전자

SK hynix

LX Semicon

TELEDYNE

PIXELPLUS

DB HiTek

Magnachip

Gpixel

SMARTSENS

ABOV SEMICONDUCTOR

POWERMASTER SEMICONDUCTOR

LUXIMA TECHNOLOGY

BYD BYD Microelectronics Co., Ltd.

SK powertech

Littelfuse® Expertise Applied | Answers Delivered

Specialized CMOS Image Sensor Company! CLAIRPIXEL

GALAXYCORE CMOS

fitipower

鴻家科技 GaN Power Tech

meerecompany

ADVANCED
GLOBAL
PACKAGE

Trusted Partner for CIS Assembly

Company Overview

Advanced Global Package

Executive Summary
AGP is the CIS assembly company located in Cheong-ju

Overview Of AGP

Advanced Global Package

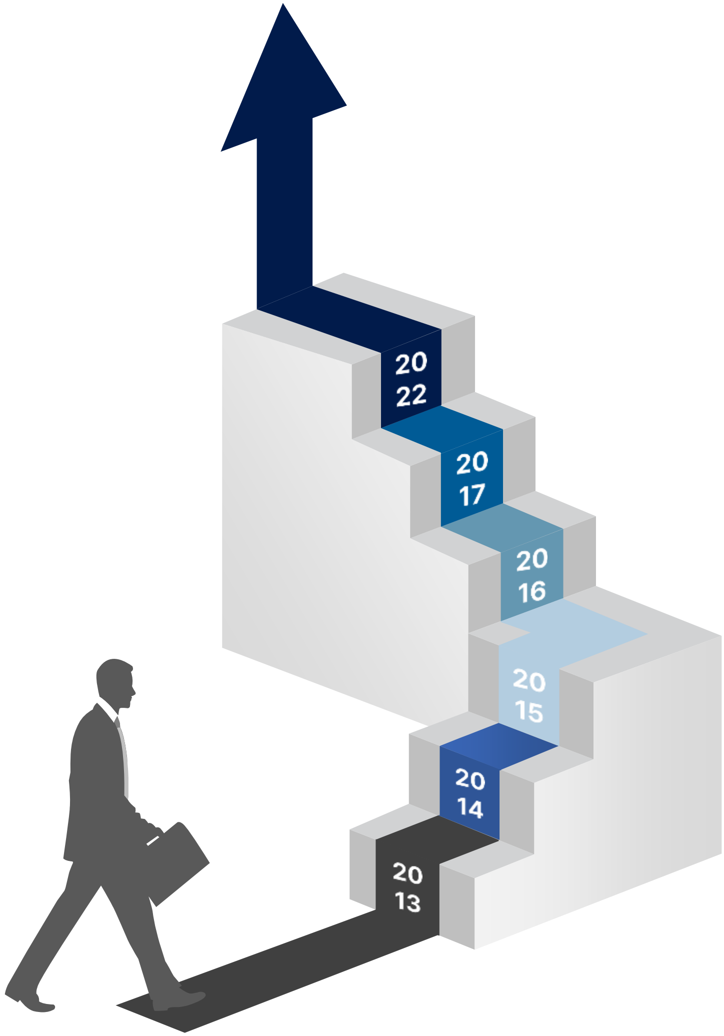
Company Name	**AGP Co., Ltd**
CEO	**BT Chun**
Establishment	**2013.06.10**
Business	**Assembly and Test Service for Optic Sensor such as Image Sensor** **Feasibility : BGA, PGA, LGA, CLCC and PLCC, LCC (Leadless Chip Carrier)**
Address	**82-19 Gwahaksaneop 1-ro, Oksan-myeon, Heungdeok-gu**
Employees	**70**
Homepage	**www.agp-s.kr**
Tel.	**+82-43-711-2600**

- AGP is located in the same building with ALT (ALT Co, Ltd.) as a child company.
- Full Turn Key Service of CIS Test(ALT) and Assembly(AGP)

Milestone

Advanced Global Package

Executive Summary
AGP' biz scope is being extended **to automotive market** and MVS from Security since



Qual & Patent
AEC-Q100-G2 Automotive向 BGA

Production Record
4,000K/month

Patent
Transparent Epoxy mold assembly method

Pixelplus社 - Mass Production
SST社- Mass Production

Patent
Anti-thermal damage CBGA

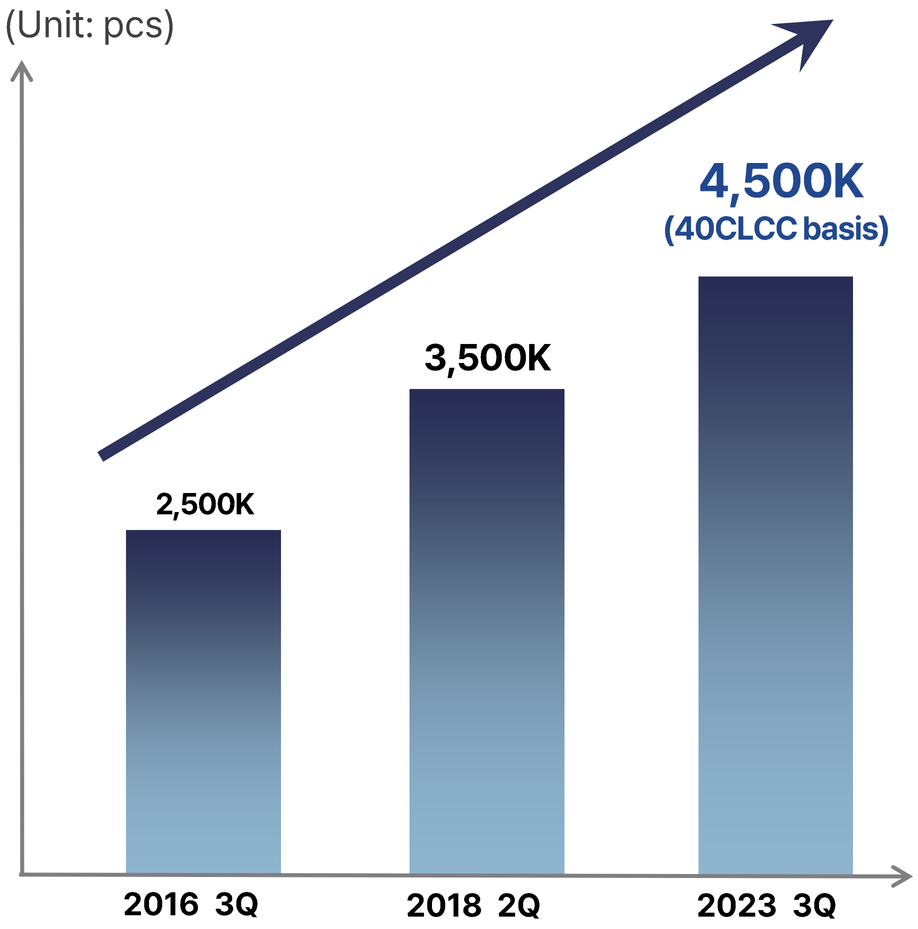
Brigate社 - Mass Production

Assembly Capacity

Advanced Global Package

Executive Summary
AGP has 5,000Kpcs assembly capacity such as CLCC 4,500K and BGA 500Kpcs per month.

Assembly Monthly Capacity



Equipment

*** On Hand : Flip-chip Bonder , Solder Ball Mounter, Stud Bump**

Process	Q'ty
Sawing	5set
Boat loading	3set
Die Attach	5set
Wire Bonding	26set
Glass Attach	6set
Laser Marking	3set
Total	48set

Assembly Process

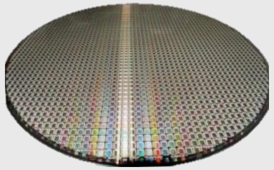
Advanced Global Package

Executive Summary
AGP has the CLCC assembly process as follows

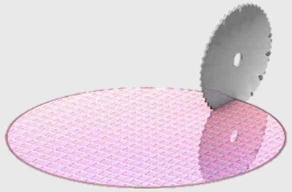
PKG Process Flow (CLCC)

***Class 10 Zone**

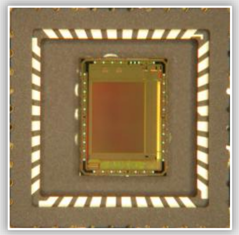
01



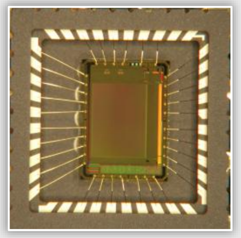
02 Wafer, Glass Sawing



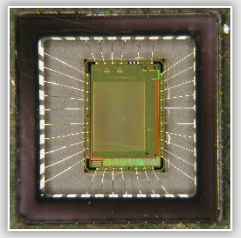
03 Die Attach



04 Wire Bond



05 Glass Attach

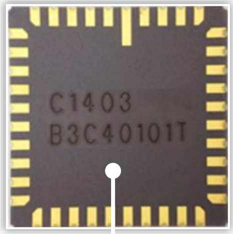


(CLCC : Ceramic Leadless Chip Carrier)

06 Final Test

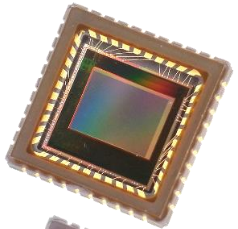
Class 1,000 Zone

07 Marking

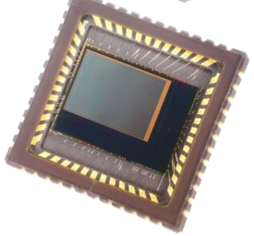


laser marking

08 Packing



Type	40 CLCC
Lead Quantity	40 Leads
Size (mm)	10.16SQ x 1.60(T)
Substrate	Ceramic



Type	48 CLCC
Lead Quantity	48 Leads
Size (mm)	14.22SQ x 1.65(T)
Substrate	Ceramic

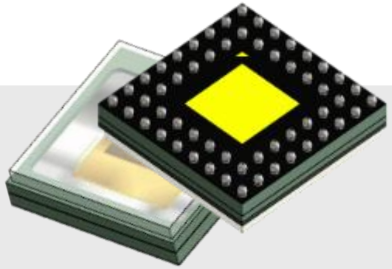
BGA Line

Advanced Global Package

Executive Summary
AGP has the PKG Line-up such as MCP_BGA of ceramic and BGA&LGA of Ceramic.

BGA PKG Process

BGA is a process of attaching a solder ball to the PKG bottom surface so that customers can work on SMT.



Process Flow

Stencil Flux Print
- Squeeze

➡

Solder Ball Drop
- Stencil Mask jig

➡

Reflow
- N2

Capacity

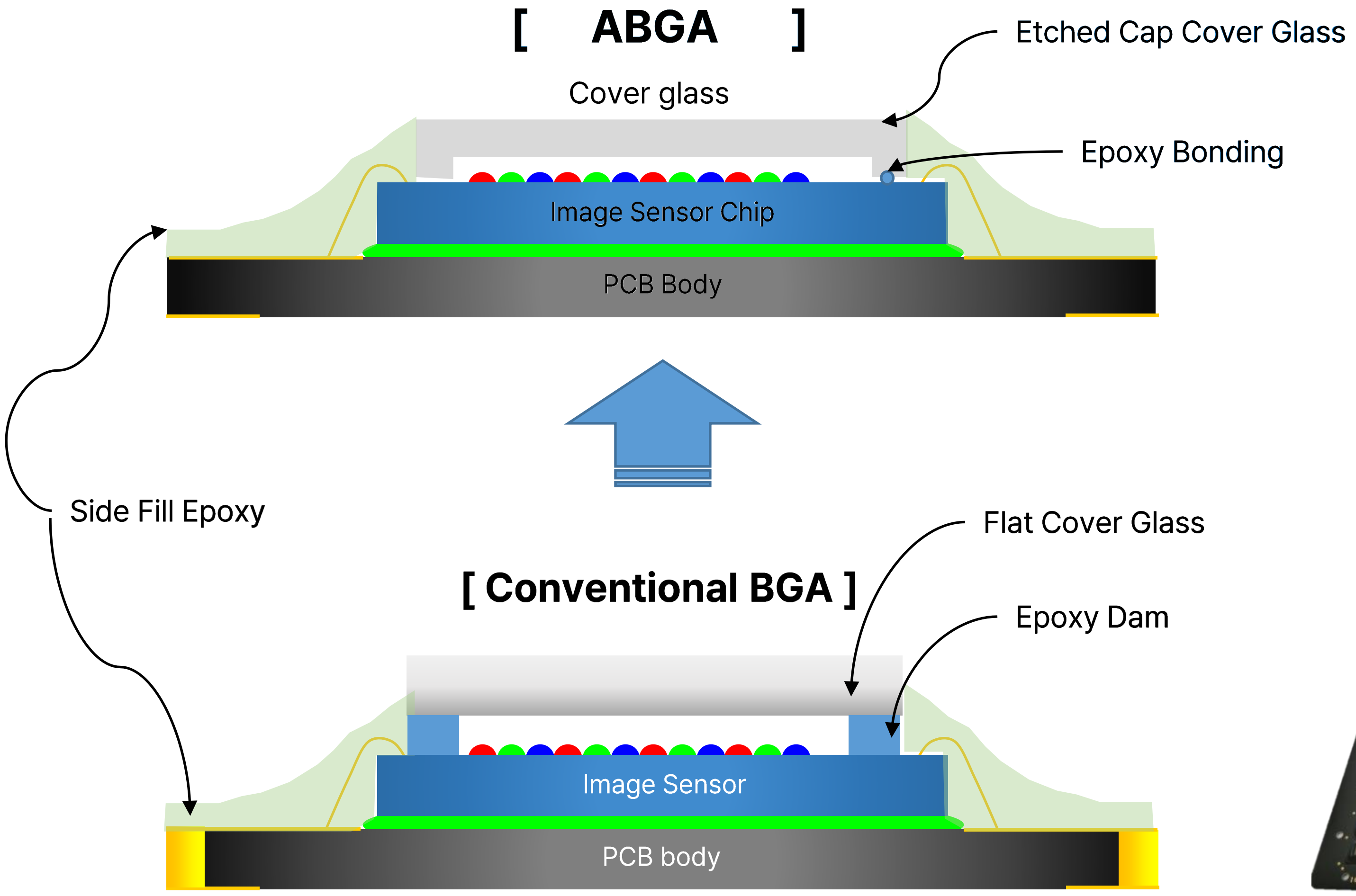
- 600K ea/Month *CLCC 10mmSQ , Φ0.5mm, 130 ball
- Applicable ball size : min Φ200um
- Area : 40sqm , Line Class 1,000

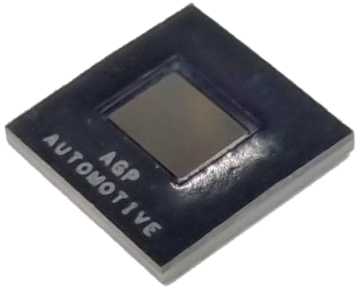
Brand New
BGA PKG

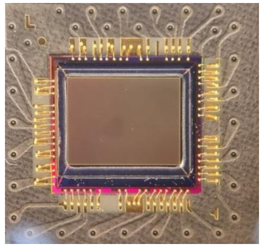
Advanced Global Package

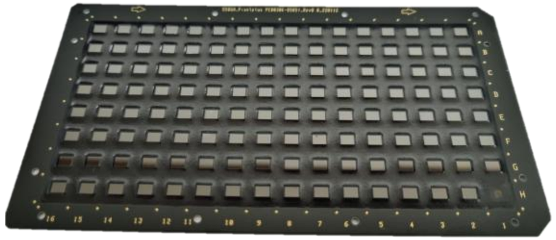
Executive Summary
AGP's BGA PKG has a specialty using a etched glass lid to clear potential particle source.

BGA PKG Process







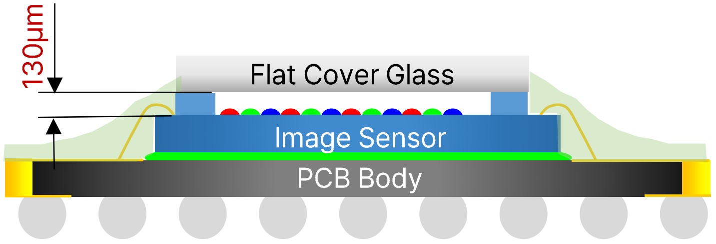
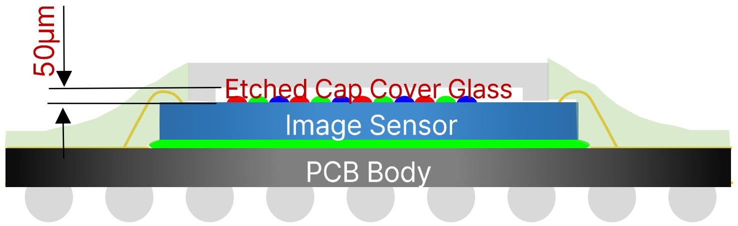
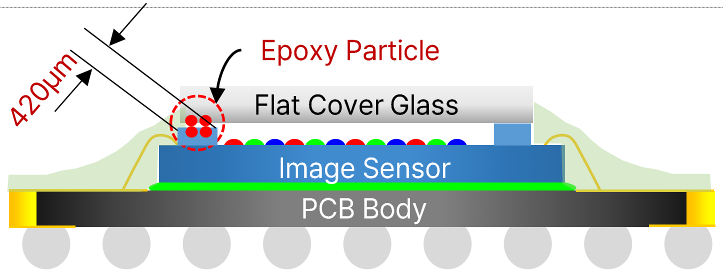
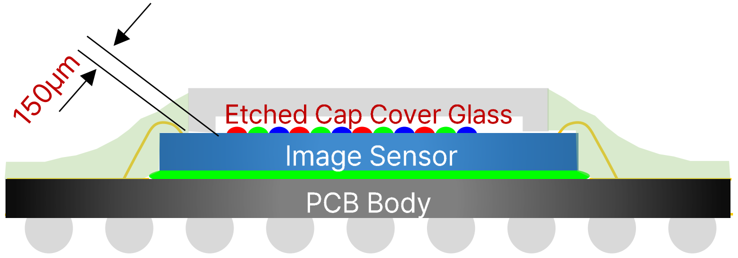
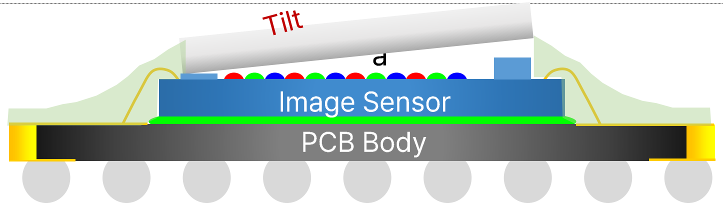
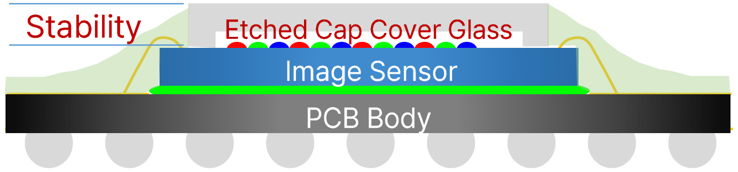


MCP_BGA
CLGA,CBGA
Advanced Global Package

Executive Summary
AGP's BGA PKG has a lot of specialties using a etched glass as followings

Specialty of ABGA'

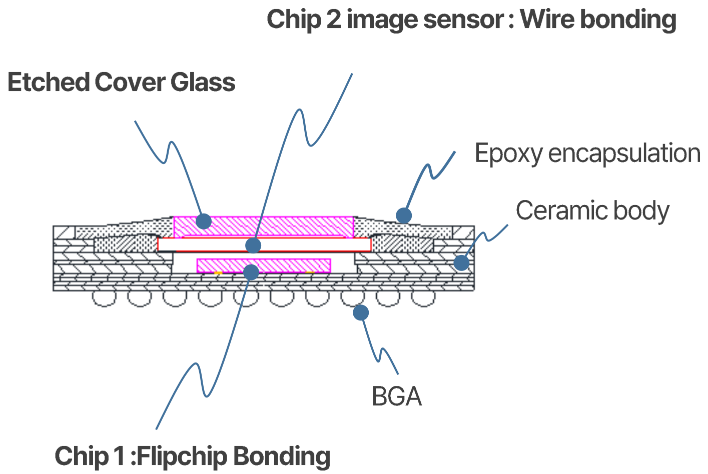
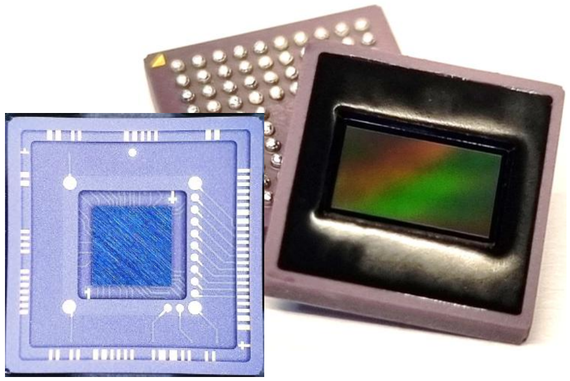
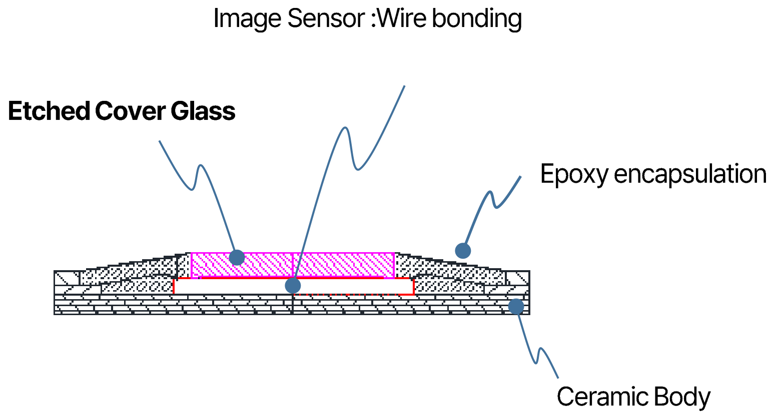
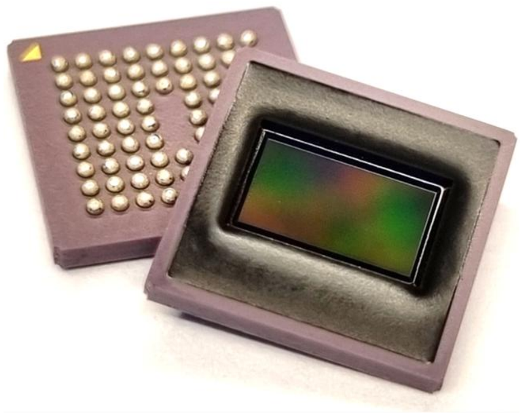
1. Air **cavity volume is 50%** of iBGA/iM2BGA: **Strong against Condensation** and good performance for light bandpass
2. Etched glass dam make to **clear any moving particle** inside the air cavity of PKG body.
3. Minimized **dam width,150μm**, make it some **flexibility in the Chip and PKG design.**
4. **Etched glass dam** make it **stable** rather than epoxy dam on the PCB body.
5. **1month PKG development lead time** make it **time-to-market** by customer **without RDL or mold process.**

Item	Im2BGA (K***@TW)	iBGA (U***@Sig)	ABGA (AGP@KR)
Air Cavity (Condensation, internal pressure)			
Moving Particle			
Dam width			
Glass Stability			

MCP_BGA
CLGA,CBGA

Advanced Global Package

MCP_BGA & CLGA & CBGA

PKG Type	Illustration	Image
MCP_BGA		
CLGA & CBGA		

Executive Summary
AGP has the PKG Line-up such as MCP_BGA of ceramic and BGA&LGA of Ceramic.

CIS-PKG

Co2 MicroJet Cleaner for Glass Lid Cleaning

Advanced Global Package

Executive Summary
As these four phenomena repeat simultaneously, foreign materials are removed

1. Physical Blasting

CO2 Snow & Pellet is sprayed with high-speed compressed air.
Removal of contamination by collision with surface contamination particles

2. Thermal shock

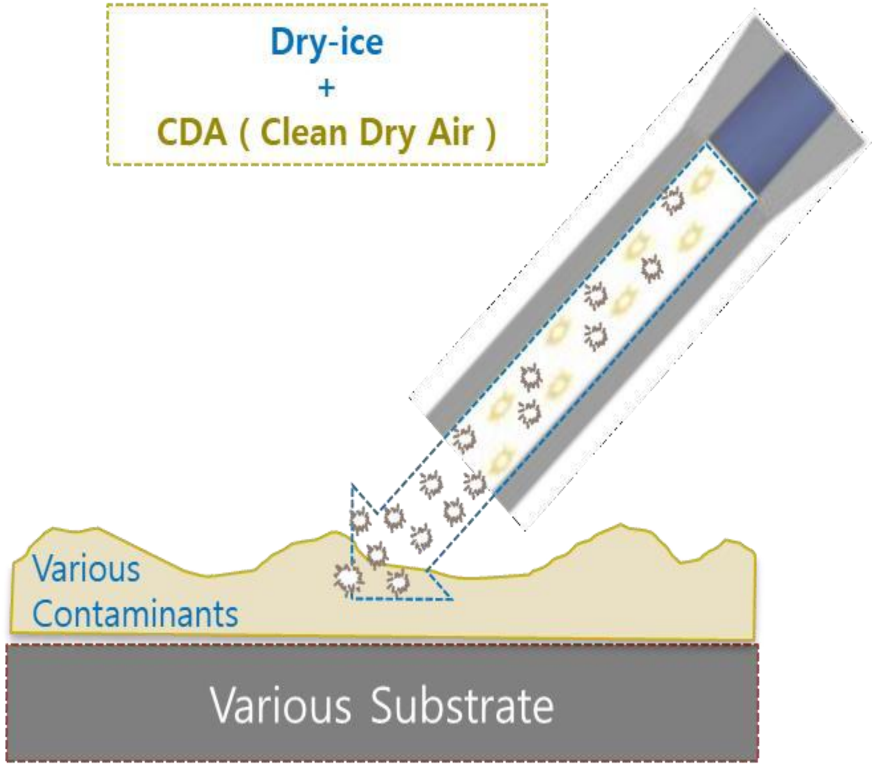
At the sublimation point: -78.5°C
Cooling and shrinking of the contaminated film by low-temperature air currents cause cracks in the film.

3. Sublimation expansion

Isolation between surface and pollutants during CO2 sublimation expansion

4. Solubility of pollutants (Organic solubility)

Solubility of organic substances (Solubility coefficient: 23)
L-CO2 has a solubility similar to that of acetone (IPA).



Configuration

Final Test

Advanced Global Package

Executive Summary

AGP's Final Test Configuration is as followings with 2set

Final Tester Config

Class 1K zone

#1 : IP750EMP + NS8080MS (Cold option) : Digital 256ch, DPS32ch, AW1000(100x45mm)
#2 : IP750EP + AL0408NT (N/A) : Digital 128ch, DPS16ch, AW1000(100x45mm)

Teradyne IP750EMP

Image Sensor Test System
Teradyne IP750EMP Tester includes IPC *4 plus Workstation.
The Teradyne IP750EMP is the second generation image sensor tester from Teradyne, offering faster capture and processing of image sensor test data. Please contact us for additional information.

Features:
License Configuration-
Digital clock: 100 MHz
Image capture clock for ICUD clock: 50 MHz
DPS CH: 32
Digital CH: 256
LVM Size: 16

HIGH SPEED IC HANDLER

MODEL NS-8080MS
SYSTEM NO. 121600
POWER SOURCE 200-240 VAC(SINGLE PHASE)
50/60Hz, 6KVA max
AIR 0.49MPa (5Kgf/cm²) 120 NQ/min
MOTOR
INPUT/OUTPUT MAIN axis 750W(AC SERVO)
INPUT/OUTPUT ARM axis 200W(AC SERVO)
HAND XZ axis 2W(STEPPING)
TEST ARM Y axis 200W(AC SERVO)
Z,U axis 750W(AC SERVO)
SHUTTLE 200W(AC SERVO)
TRAY HANDLING ROBOT 200W(AC SERVO)
TRAY L/RL/UL 6W(INDUCTION)
FIX TRAY 2W (STEPPING)

DIMENSIONS W1850×D1500×H1970
WEIGHT APPROX. 1090 kg
DATE 15.04 .

SEIKO EPSON CORP.
3-5, Owa 3-chome, Suwa-shi,
Nagano-ken, 392-8502 JAPAN
N8-1

Process

Final Test

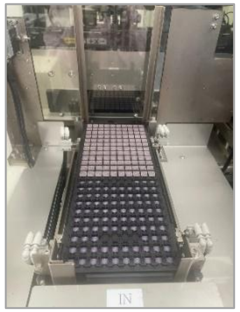
Advanced Global Package

Executive Summary
AGP has the final test process as followings in the class 1000 clean room

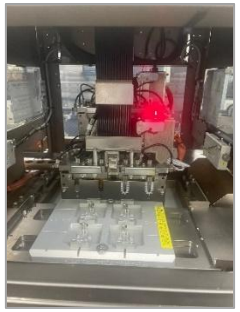
Final Test Process

Class 1K zone

01 Tray Loading



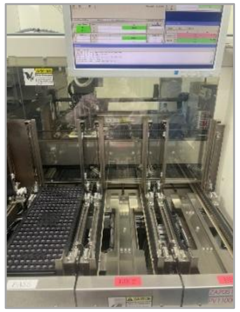
02 PKG Pick-up



03 Auto Test (Hot test)

04 PKG Bin Split

05 Tray Unloading



06 Manual VT (Fail bin only)

07 Bake

08 FVI

09 Protection film Attach

10 Packing

Reliability Equipment

Advanced Global Package

Executive Summary
AGP has the key reliability equipment to shorten the evaluation period of PKG reliability experiment

Reliability Equipment

Reliability Item	THC Temperature Humidity Chamber (constant temp .& humidity test)	PCT / U-HAST Pressure Cooker Test (high temp. & high pressure test)	T/C Temperature Cycling (thermal shock test)
Equipment			
SPEC	. Model : YM-THC 420S . Temp Rang : -40°C~+150°C . Humidity Rang : 30~98% R.H . Out Size : 1250(W)×1150(D) ×1650(H)mm . Electricity : AC380V, 60Hz, 3ø / 12KW . Water is used in the machine	. Model : YM-PCT 600 . Temp Rang : 85°C~150°C . Humidity Rang : 75%~100% R.H . Steam Pressure : 3 atm. . Out Size : 1350(W)×1150(D) ×1750(H)mm . Electricity : AC220V, 60Hz, 3ø / 10KW . Water is used in the machine	. Model : YM-TST600 (2 Zone) . Temp Rang : -70°C~+150°C . Out Size : 1600(W)×1400(D) ×2050(H)mm . Electricity : AC380V 60Hz, 3ø / 30KW . Compressed air is used in the machine

Customers

Advanced Global Package

TELEDYNE

PIXELPLUS

LUXIMA
TECHNOLOGY

昆山锐芯微电子
BRIGATES INC

LX Semicon

BYD

SMARTSENS

DB HiTek

GALAXYCORE
CMOS

Gpixel

Specialized CMOS Image Sensor Company!
CLAIRPIXEL

meere company

Quality System

Advanced Global Package

ISO14001:2015

CERTIFICATE
OF REGISTRATION

This is to certify that:

AGP Co., Ltd.

82-19, Gwahaksaneop 1-ro, Oksan-myeon, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28122, Republic of Korea

operates an

ENVIRONMENTAL MANAGEMENT SYSTEM

which complies with the requirements of

ISO 14001:2015

for the following scope

Manufacture of CLCC(Ceramic Leadless Chip Carriers) and PLCC(Plastic Leadless Chip Carriers)

Certificate No: EMS41079

Issued: 27 April 2021
Expires: 3 May 2024

Originally Certified: 4 May 2015
Current Certification: 27 April 2021

Frank Camasta
Global Head of Technical Services
SAI Global Assurance

Certified System
ISO 14001

JAS-ANZ
WWW.JAS-ANZ.ORG/REGISTER

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IATF16949:2016

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OF REGISTRATION

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3F, 82-19, Gwahaksaneop 1-ro, Oksan-myeon, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28122, Republic of Korea

Operates a

QUALITY MANAGEMENT SYSTEM

Which complies with the requirements of

IATF 16949:2016

For the following scope of registration:

The manufacture of CLCC (ceramic leadless chip carriers)
and PLCC (plastic leadless chip carriers). Exclusions-product design.

Certificate No.: AUTO40956
IATF Database No.: 0436056

Issue Date: 25 November 2021
Expiry Date: 24 November 2024

Frank Camasta
Global Head of Technical Services
SAI Global Assurance

Dusan Nikolic
Automotive Technical Manager
Global Scheme Owner

Certified System
IATF 16949

Registered by:

SAI GLOBAL

ISO9001:2015

CERTIFICATE
OF REGISTRATION

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AGP Co., Ltd.

3F, 82-19, Gwahaksaneop 1-ro, Oksan-myeon, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28122, Republic of Korea

operates a

QUALITY MANAGEMENT SYSTEM

which complies with the requirements of

ISO 9001:2015

for the following scope

The manufacture of CLCC (ceramic leadless chip carriers)
and PLCC (plastic leadless chip carriers). Exclusions-product design.

Certificate No: QMS43357

Issued: 25 November 2021
Expires: 24 November 2024

Originally Certified: 5 December 2018
Current Certification: 25 November 2021

Frank Camasta
Global Head of Technical Services
SAI Global Assurance

Certified System
ISO 9001

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Thanks for your attention